MBRD620CT, MBRD640CT and MBRD660CT are Preferred Devices

# SWITCHMODE Power Rectifiers

# DPAK-3 Surface Mount Package

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

#### Features

- Extremely Fast Switching
- Extremely Low Forward Drop
- Platinum Barrier with Avalanche Guardrings
- Pb–Free Packages are Available

#### Mechanical Characteristics:

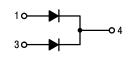
- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



### **ON Semiconductor®**

http://onsemi.com

# SCHOTTKY BARRIER RECTIFIERS 6.0 AMPERES, 20 – 60 VOLTS

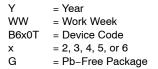




DPAK CASE 369C

#### MARKING DIAGRAM





#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

**Preferred** devices are recommended choices for future use and best overall value.

#### MAXIMUM RATINGS

		MBRD					
Rating	Symbol	620CT	630CT	640CT	650CT	660CT	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	20	30	40	50	60	V
Average Rectified Forward CurrentPer Diode $T_C = 130^{\circ}C$ (Rated $V_R$ )Per Device	I <sub>F(AV)</sub>	3 6				A	
Peak Repetitive Forward Current, T <sub>C</sub> = 130°C (Rated V <sub>R</sub> , Square Wave, 20 kHz) Per Diode	I <sub>FRM</sub>	6			A		
Nonrepetitive Peak Surge Current – (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		75			A		
Peak Repetitive Reverse Surge Current (2 $\mu$ s, 1 kHz)		1			А		
Operating Junction Temperature (Note 1)		-65 to +175			°C		
Storage Temperature		-65 to +175				°C	
Voltage Rate of Change (Rated V <sub>R</sub> )		10,000			V/μs		
THERMAL CHARACTERISTICS PER DIODE	-	-					
Rating	Symbol			Value			Unit
Maximum Thermal Resistance, Junction-to-Case		6			°C/W		
	-	1					

 $R_{\theta JA}$ 

VF

i<sub>R</sub>

°C/W

V

mΑ

80

0.7

0.65 0.9 0.85

0.1

15

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

2. Rating applies when surface mounted on the minimum pad size recommended.

Maximum Thermal Resistance, Junction-to-Ambient (Note 2)

ELECTRICAL CHARACTERISTICS PER DIODE

Maximum Instantaneous Forward Voltage (Note 3)

Maximum Instantaneous Reverse Current (Note 3)

 $i_F$  = 3 Amps,  $T_C$  = 25°C

 $i_F = 3 \text{ Amps, } T_C = 25^{\circ}C$   $i_F = 3 \text{ Amps, } T_C = 125^{\circ}C$   $i_F = 6 \text{ Amps, } T_C = 25^{\circ}C$   $i_F = 6 \text{ Amps, } T_C = 125^{\circ}C$ 

(Rated dc Voltage,  $T_C = 25^{\circ}C$ )

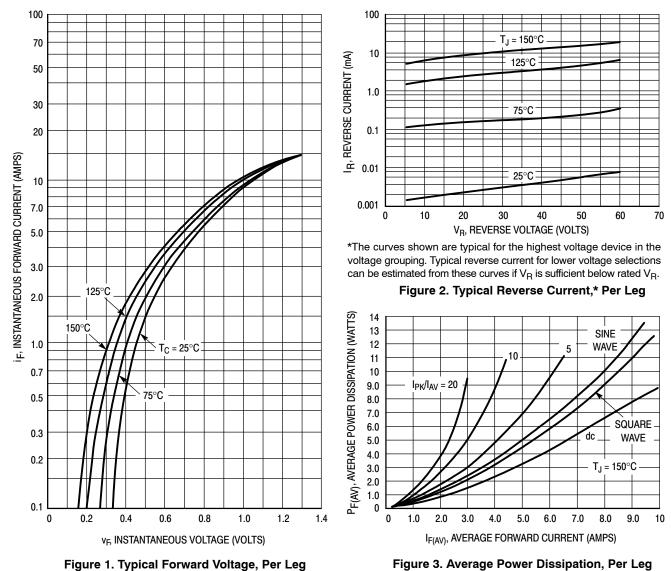
(Rated dc Voltage,  $T_C = 125^{\circ}C$ )

3. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>		
MBRD620CTT4	DPAK	2500 Tape & Reel		
MBRD620CTT4G	DPAK (Pb-Free)	2500 Tape & Reel		
MBRD630CTT4	DPAK-3	2500 Tape & Reel		
MBRD630CTT4G	DPAK (Pb-Free)	2500 Tape & Reel		
MBRD640CT	DPAK-3	75 Units / Rail		
MBRD640CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
MBRD640CTT4	DPAK-3	2500 Tape & Reel		
MBRD640CTT4G	DPAK-3 (Pb-Free)	2500 Tape & Reel		
MBRD650CT	DPAK-3	75 Units / Rail		
MBRD650CTG	DPAK (Pb-Free)	75 Units / Rail		
MBRD650CTT4	DPAK-3	2500 Tape & Reel		
MBRD650CTT4G	DPAK (Pb-Free)	2500 Tape & Reel		
MBRD660CT	DPAK-3	75 Units / Rail		
MBRD660CTG	DPAK-3 (Pb-Free)	75 Units / Rail		
MBRD660CTRL	DPAK-3	1800 Tape & Reel		
MBRD660CTRLG	DPAK-3 (Pb-Free)	1800 Tape & Reel		
MBRD660CTT4	DPAK-3	2500 Tape & Reel		
MBRD660CTT4G	DPAK–3 (Pb–Free)	2500 Tape & Reel		
8				

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



#### **TYPICAL CHARACTERISTICS**

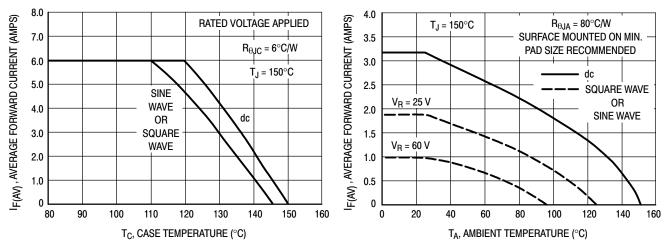




Figure 5. Current Derating, Ambient, Per Leg

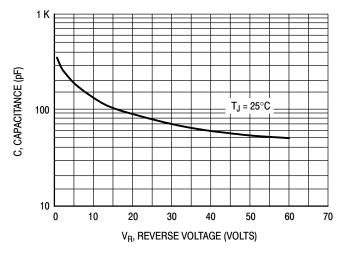
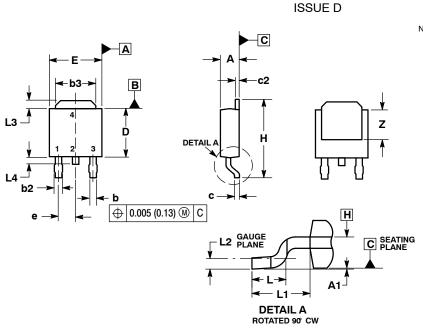


Figure 6. Typical Capacitance, Per Leg

#### PACKAGE DIMENSIONS

**DPAK (SINGLE GAUGE)** CASE 369C-01

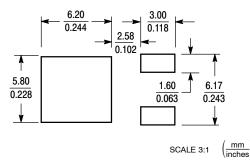


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN
- DIMENSIONS b3, L3 and Z. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY. 6. DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.086	0.094	2.18	2.38		
A1	0.000	0.005	0.00	0.13		
b	0.025	0.035	0.63	0.89		
b2	0.030	0.045	0.76	1.14		
b3	0.180	0.215	4.57	5.46		
с	0.018	0.024	0.46	0.61		
c2	0.018	0.024	0.46	0.61		
D	0.235	0.245	5.97	6.22		
E	0.250	0.265	6.35	6.73		
е	0.090 BSC		2.29 BSC			
Н	0.370	0.410	9.40	10.41		
L	0.055	0.070	1.40	1.78		
L1	0.108 REF		2.74 REF			
L2	0.020	0.020 BSC		0.51 BSC		
L3	0.035	0.050	0.89	1.27		
L4		0.040		1.01		
Z	0.155		3.93			

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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